



Material Content Data Sheet



Sales Product Name		BSL211SP H6327		Issued		2. August 2018		
MA#		MA001189502						
Package		PG-TSOP6-6-6		Weight*		13.59 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.009	0.07		690	
	noble metal	gold	7440-57-5	0.036	0.27		2675	
	inorganic material	silicon	7440-21-3	0.412	3.03	3.37	30314	33679
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		87	
	non noble metal	titanium	7440-32-6	0.006	0.04		435	
	non noble metal	chromium	7440-47-3	0.018	0.13		1304	
	non noble metal	copper	7440-50-8	5.882	43.28	43.46	432845	434671
wire	non noble metal	copper	7440-50-8	0.039	0.29	0.29	2888	2888
encapsulation	organic material	carbon black	1333-86-4	0.067	0.49		4938	
	plastics	epoxy resin	-	1.443	10.62		106165	
	inorganic material	silicondioxide	60676-86-0	5.201	38.27	49.38	382690	493793
leadfinish	non noble metal	tin	7440-31-5	0.299	2.20	2.20	21996	21996
plating	noble metal	silver	7440-22-4	0.176	1.30	1.30	12973	12973
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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